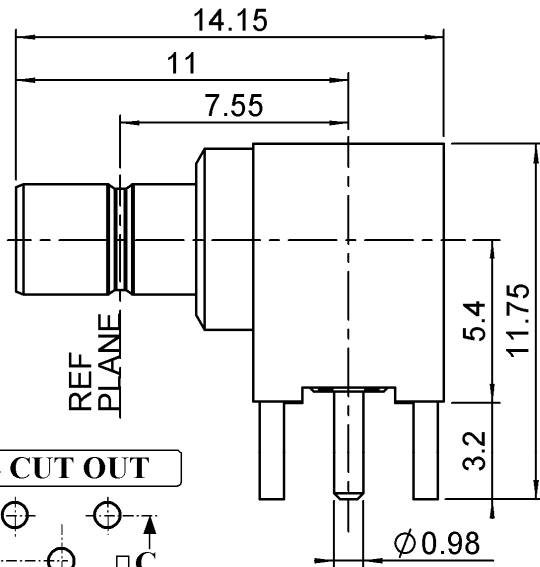
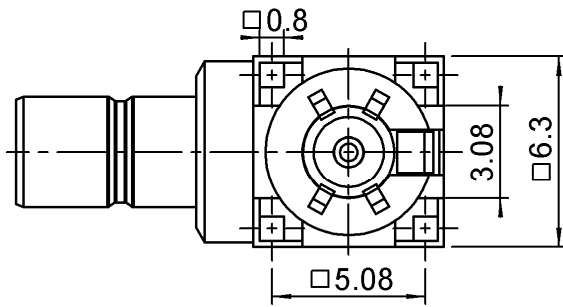


R/A MALE RECEPTACLE FOR PCB

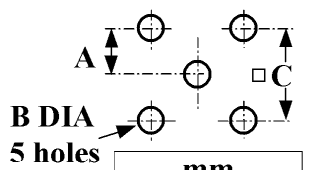
R114.665.230

PIN IN PASTE VERSION

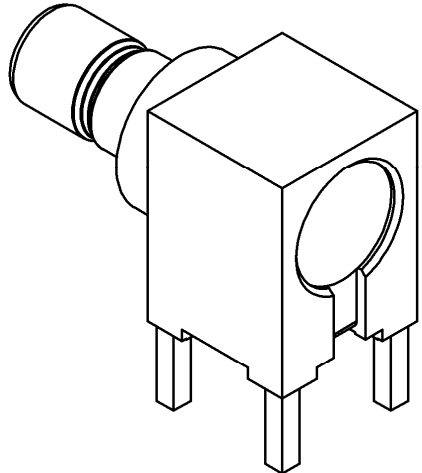
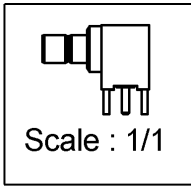
Series : SMB



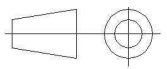
PANEL CUT OUT



	mm	
	Maxi	mini
A	2.59	2.49
B	1.4	1.3
C	5.16	5



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (µm)
BODY	BRASS	GOLD 0.2 OVER NICKEL 2
CENTER CONTACT	BRASS	GOLD 1.3 OVER NICKEL 2.54 OVER COPPER 3
OUTER CONTACT		
INSULATOR	PTFE	
GASKET		
OTHERS PARTS	BRASS	GOLD 0.2 OVER NICKEL 2-
-	-	-
-	-	-

Issue : 0824 A

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



R/A MALE RECEPTACLE FOR PCB

R114.665.230

PIN IN PASTE VERSION

Series : **SMB**

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	50	Ω
Frequency	0-4	GHz
VSWR	*1.20 + 0.0000	x F(GHz) Maxi
Insertion loss	*0.25	$\sqrt{F(GHz)}$ dB Maxi
RF leakage	- (NA)	- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	1000	Veff mini
Insulation resistance	1000	M Ω mini

Operating temperature	-65/+165	$^{\circ}$ C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHER CHARACTERISTICS

Assembly instruction

Others :

*coaxial transmission line only
compliant with MSL 1

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	10	N mini
Axial force – Opposite end	10	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	500	Cycles mini
Weight	2.8000	g

Issue : 0824 A

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R/A MALE RECEPTACLE FOR PCB

R114.665.230

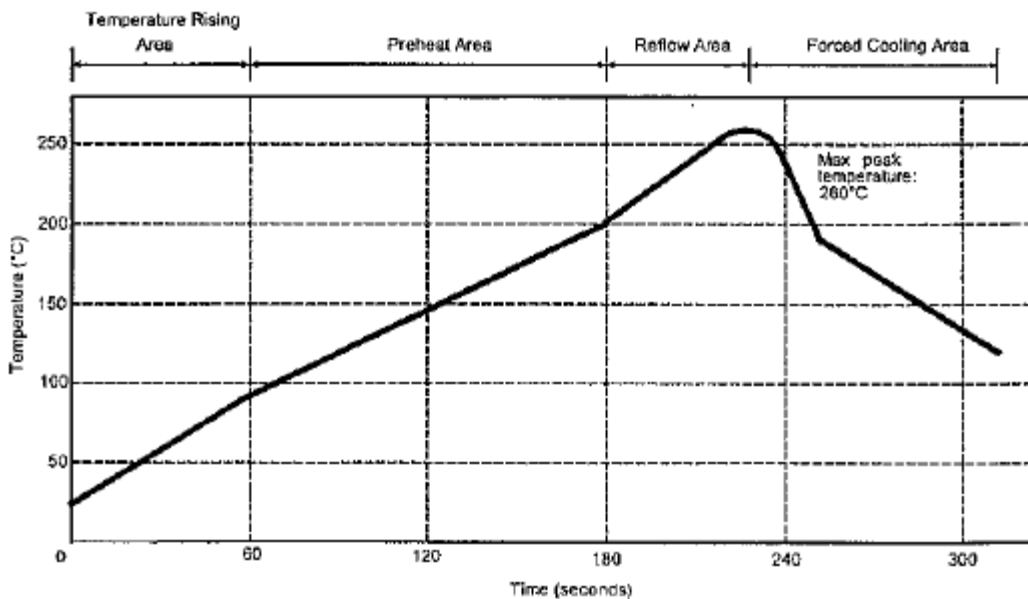
PIN IN PASTE VERSION

Series : **SMB**

SOLDER PROCEDURE

1. Deposition of solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 microns mini (0.005 inch).
Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type.
Video camera is recommended for the positioning of the component.
Adhesive agents must not be used on the receptacle.
3. Soldering by infra-red reflow.
Below, please find the typical profile to use.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1-4	° C/sec
Max Peak Temperature	260	° C
Max dwell time @260° C	10	sec
Min dwell time @235° C	20	sec
Max dwell time @235° C	60	sec
Temperature drop in cooling Area	-1 to-4	° C/sec
Max dwell time above 100° C	420	sec

Issue : 0824 A

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